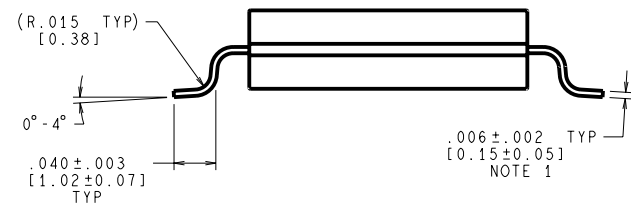
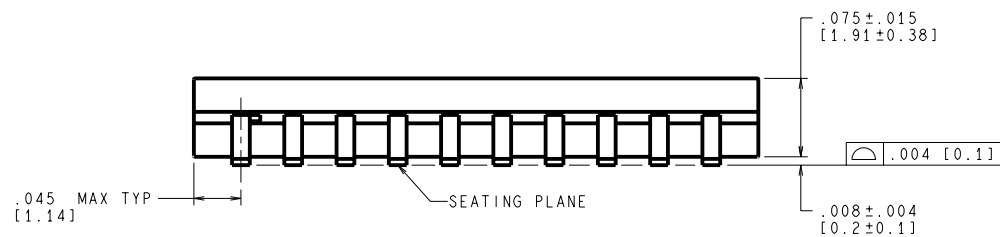
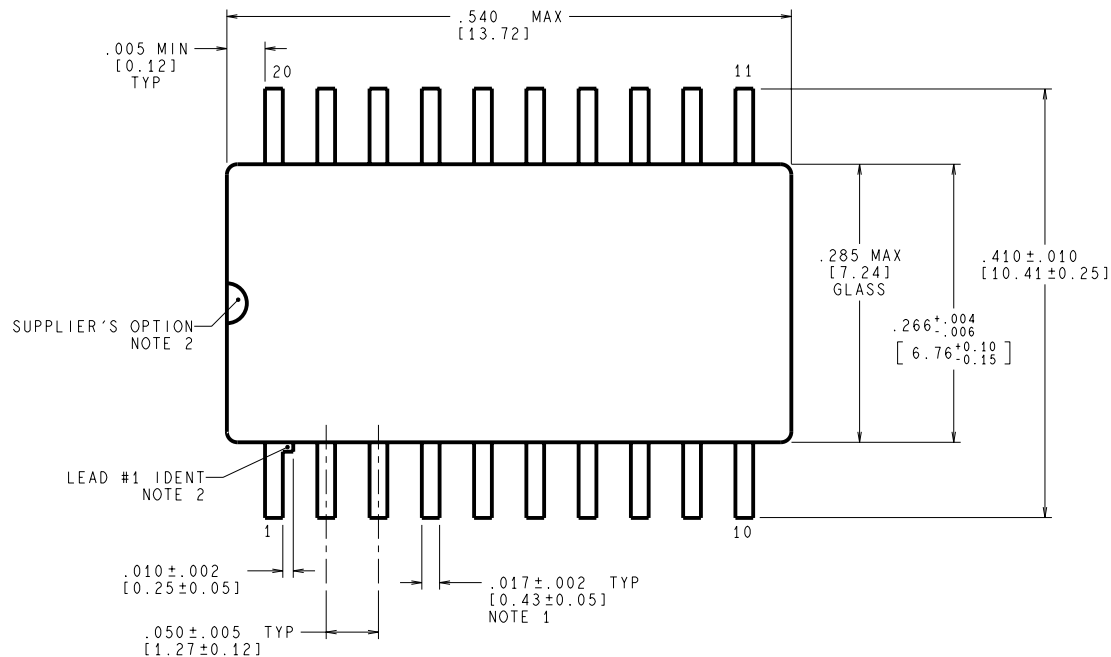


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11842	10/13/1997	TL/KH
B	DIM .410 WAS .391; UPDATE NOTE 3.	12013	06/15/1998	MS/



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
2. LEAD 1 IDENTIFICATION SHALL BE:
 - a) A NOTCH OR OTHER MARK WITHIN THIS AREA
 - b) A TAB ON LEAD 1, EITHER SIDE
3. NO JEDEC REGISTRATION AS OF JUNE 1998.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS		DATE	National Semiconductor		
DRAWN T. LEQUANG		10/13/1997	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.			CERPACK, 20 LEAD, GULL WING		
ENGR. CHK.					
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-WG20A	REV B
		DO NOT SCALE DRAWING SHEET 1 of 1			